

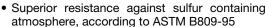
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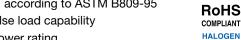
Sulfur Resistant, Pulse Proof, High Power **Thick Film Chip Resistors**

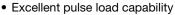


The sulfur resistant, high power thick film chip resistors series combines the capability to stand harsh environment operation with high power rating and excellent pulse load performance, being the perfect choice for power measurement electronics.

FEATURES







- Enhanced power rating
- Double sided printed resistor element
- AEC-Q200 qualified
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- Automotive
- Industrial
- Commercial
- High power
- · Harsh environmental

DESCRIPTION	RCA0402-HP	RCA0603-HP	RCA0805-HP	RCA1206-HP	RCA1210-HP	RCA1218-HP	RCA2010-HP	RCA2512-HP
DESCRIPTION	e3	e3	e3	e3	e3	e3	e3	e3
Imperial size	0402	0603	0805	1206	1210	1218	2010	2512
Metric size code	RR1005M	RR1608M	RR2012M	RR3216M	RR3225M	RR3246M	RR5025M	RR6332M
Resistance range				1 Ω to	1 ΜΩ			
Resistance tolerance				± 5 %	; ± 1 %			
Temperature coefficient				± 200 ppm/K	; ± 100 ppm/K			
Rated dissipation, P ₇₀ (1)	0.2 W ⁽²⁾	0.33 W	0.5 W	0.75 W ⁽³⁾	0.75 W	1.5 W	1.0 W	1.5 W
Operating voltage, <i>U</i> _{max.} AC _{RMS} /DC	50 V	75 V	150 V	200 V	200 V	200 V	400 V	500 V
Permissible film temperature, $\mathcal{G}_{F \text{ max.}}^{(1)}$		155 °C						
Operating temperature range				-55 °C to	+155 °C			
Max. resistance change at P_{70} for resistance range, $ \Delta R/R $ after:				≤ 2.	0 %			
8000 h	≤ 4.0 %							
Permissible voltage against ambient (insulation):								
1 min, U _{ins}	75 V	100 V	200 V	300 V	300 V	300 V	300 V	300 V

Notes

- (1) Please refer to APPLICATION INFORMATION below
- (2) RCA0402-HP resistors feature a single side printed resistive layer only
- (3) Specified power rating requires a thermal resistance of $R_{th} = 110 \text{ K/W}$

APPLICATION INFORMATION

When the resistor dissipates power, a temperature rise above the ambient temperature occurs, dependent on the thermal resistance of the assembled resistor together with the printed circuit board. The rated dissipation applies only if the permitted film temperature is not exceeded.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.



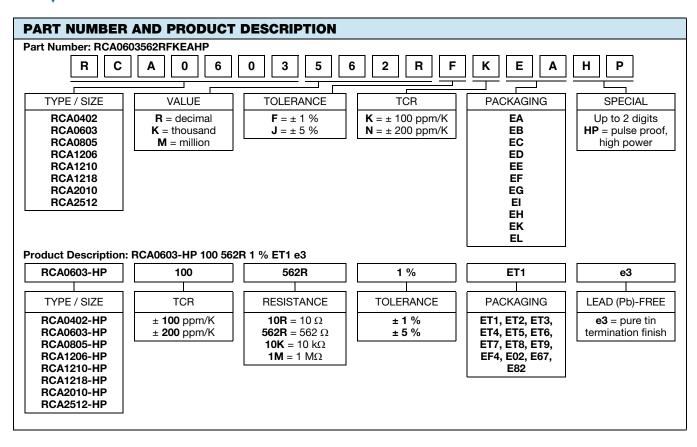
TEMPERATURE COEFFICIENT AND RESISTANCE RANGE							
TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES			
RCA0402-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 MΩ	E24			
NOAU402-HF 63	± 100 ppm/K	± 1 %	1 Ω to 1 M Ω	E24; E96			
RCA0603-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 M Ω	E24			
NCAUGUS-HP es	± 100 ppm/K	± 1 %	1 Ω to 1 M Ω	E24; E96			
RCA0805-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 MΩ	E24			
RCAUGUS-HP es	± 100 ppm/K	± 1 %	1 Ω to 1 MΩ	E24; E96			
RCA1206-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 M Ω	E24			
NOA1200-HF 63	± 100 ppm/K	± 1 %	1 Ω to 1 M Ω	E24; E96			
RCA1210-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 M Ω	E24			
NCA1210-HP es	± 100 ppm/K	± 1 %	1 Ω to 1 M Ω	E24; E96			
RCA1218-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 MΩ	E24			
RCA1216-HP es	± 100 ppm/K	± 1 %	1 Ω to 1 MΩ	E24; E96			
RCA2010-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 MΩ	E24			
NOAZUIU-HP 63	± 100 ppm/K	± 1 %	1 Ω to 1 MΩ	E24; E96			
RCA2512-HP e3	± 200 ppm/K	± 5 %	1 Ω to 1 MΩ	E24			
NOAZUIZ-NP 63	± 100 ppm/K	± 1 %	1 Ω to 1 MΩ	E24; E96			

PACKAGING						
TYPE / SIZE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS
RCA0402-HP e3	ED = ET7	10 000			2 mm	Ø 180 mm / 7"
RCAU4U2-HP e3	EE = EF4	50 000			2 111111	Ø 330 mm / 13"
	EI = ET2	5000				Ø 180 mm / 7"
	ED = ET3	10 000			2 mm	Ø 180 mm / 7"
	EL = ET4	20 000			2 111111	Ø 285 mm / 11.25"
RCA0603-HP e3	EE = ET8	20 000				Ø 330 mm / 13"
	EA = ET1	5000				Ø 180 mm / 7"
	EB = ET5	10 000			4 mm	Ø 285 mm / 11.25"
	EC = ET6	20 000	Paper tape acc. to	8 mm		Ø 330 mm / 13"
	EA = ET1	5000	IEC 60286-3, type 1a	OHIIII	4 mm	Ø 180 mm / 7"
RCA0805-HP e3	EB = ET5	10 000				Ø 285 mm / 11.25"
	EC = ET6	20 000				Ø 330 mm / 13"
	EA = ET1	5000				Ø 180 mm / 7"
RCA1206-HP e3	EB = ET5	10 000			4 mm	Ø 285 mm / 11.25"
	EC = ET6	20 000				Ø 330 mm / 13"
	EA = ET1	5000				Ø 180 mm / 7"
RCA1210-HP e3	EB = ET5	10 000			4 mm	Ø 285 mm / 11.25"
	EC = ET6	20 000				Ø 330 mm / 13"
RCA1218-HP e3	EK = ET9	4000			4 mm	Ø 180 mm / 7"
RCA2010-HP e3	EF = E02	4000	Blister tape acc. to	12 mm	4 mm	Ø 180 mm / 7"
RCA2512-HP e3	EG = E67	2000	IEC 60286-3, type 2a	12 111111	8 mm	Ø 180 mm / 7"
NOAZO12-NP 60	EH = E82	4000			4 mm	2 100 11111 / 1



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DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A cermet film layer and a glass-over are deposited on both sides of a high grade (Al₂O₃) ceramic substrate with its prepared inner contacts on both sides. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. A special process is used to ensure resistor long term operation in harsh environment (sulfur atmosphere). The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure on 100 % of the individual chip resistors. Only accepted products are laid directly into the tape in accordance with **IEC 60286-3 Type 1a and Type 2a** (1).

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are RoHS-compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. Solderability is specified for 2 years after production or requalification. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein (2)
- The Global Automotive Declarable Substance List (GADSL) (3)

 The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) ⁽⁴⁾ for its supply chain

The products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishay.com/how/leadfree.

Hence the products fully comply with the following directives:

- 2000/53/EC End-of-Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the Use of Hazardous Substances Directive (RoHS) with amendment 2015/863/EU
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

APPROVALS

The resistors are qualified according to AEC-Q200.

Where applicable, the resistors are tested in accordance with **EN 140401-802** which refers to **EN 60115-1**, **EN 60115-8** and the variety of environmental test procedures of the **IEC 60068** ⁽¹⁾ series.

RELATED PRODUCTS

For more information about products for non-sulfur-containing environment applications, but with superior pulse performance please refer to datasheet: D/CRCW-HP e3, Pulse Proof, High Power Thick Film Chip Resistors

www.vishav.com/doc?20043.

For thick film resistors with standard requirements for power rating, please refer to datasheet:

D/CRCW e3, Standard Thick Film Chip

www.vishay.com/doc?20035.

For anti-surge products and high power rating, please refer to datasheet:

RCS e3, Anti-Surge High Power Thick Film Chip Resistors www.vishay.com/doc?20065.

Notes

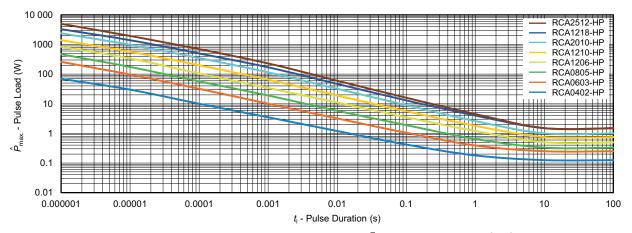
- (1) The quoted IEC standards are also released as EN standards with the same number and identical contents
- (2) The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at http://std.iec.ch/iec62474
- (3) The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org
- (4) The SVHC list is maintained by the European Chemical Agency (ECHA) and available at http://echa.europa.eu/candidate-list-table



FUNCTIONAL PERFORMANCE

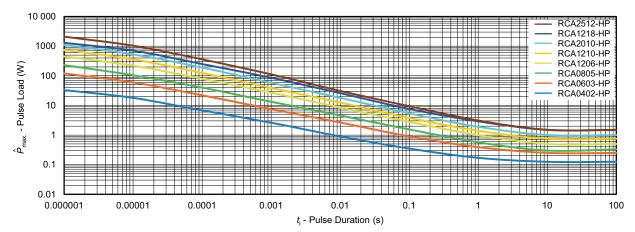
PERFORMANCE IN SULFUR-CONTAINING AMBIANCE							
TEST NAME	HUMID SULFUR VAPOR TEST	HUMID SULFUR VAPOR TEST (Accelerated)					
Reference specification	ASTM B809-95	ASTM B809-95 accelerated conditions					
Test conditions (temperature, humidity)	60 °C ± 2 °C 85 % ± 4 % RH	90 °C ± 2 °C 74 % ± 7 % RH					
Aggressive agent	Sulfur (saturated vapor)	Sulfur (saturated vapor)					
Failure criteria in VI under magnification	No silver sulfide growth at the interface between termination and protective overcoat. No signs of mechanical damage.	No silver sulfide growth at the interface between termination and protective overcoat. No signs of mechanical damage.					
Failure criteria in electrical test	≤ (± 1 % R + 0.05 Ω)	≤ (± 1 % R + 0.05 Ω)					
Time before failure	8000 h	1000 h					

Single Pulse



Maximum pulse load, single pulse; applicable if $\bar{P} \to 0$ and n < 1000 and $\hat{U} \le \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

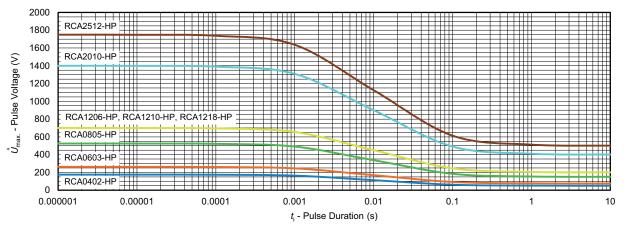
Continuous Pulse



Maximum pulse load, continuous pulses; applicable if $\bar{P} \leq P \ (\vartheta_{amb})$ and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

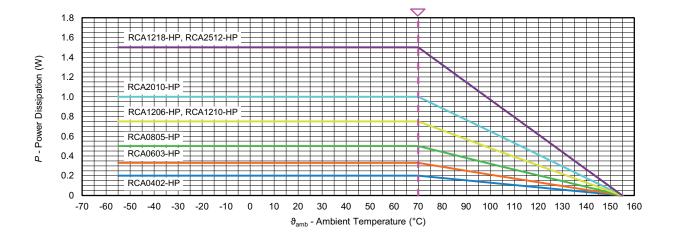


Pulse Voltage



Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P} \leq \hat{P}_{max.}$; for permissible resistance change equivalent to 8000 h operation

Derating





TESTS AND REQUIREMENTS

All executed tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 60115-8 (successor of EN 140400), sectional specification

EN 140401-802, detail specification

IEC 60068-2-xx, test methods

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-802. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

Temperature: 15 °C to 35 °C Relative humidity: 25 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on boards in accordance with EN 60115-8, 2.4.2 unless otherwise specified.

EN 60115-1 CLAUSE			TEST PROCEDURE	
			Stability for product types:	STABILITY CLASS 2 OR BETTER
			RCA-HP e3	1 Ω to 1 M Ω
4.5	-	Resistance	-	± 1 %; ± 5 %
4.8	-	Temperature coefficient	(20 / -55 / 20) °C and (20 / 155 / 20) °C	± 100 ppm/K; ± 200 ppm/K
4.25.1	_	Endurance at 70 °C	$U = \sqrt{P_{70} \times R}$ or $U = U_{\text{max.}}$; whichever is the less severe; 1.5 h on; 0.5 h off	
7.20.1		Endurance at 70°C	70 °C; 1000 h	$\pm (2 \% R + 0.1 \Omega)$
			70 °C; 8000 h	\pm (4 % R + 0.1 Ω)
4.25.3	-	Endurance at upper category temperature	155 °C, 1000 h	± (2 % R + 0.1 Ω)
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH;	± (1 % R + 0.05 Ω)
4.37	67 (Cy)	Damp heat, steady state, accelerated	(85 ± 2) °C; (85 ± 5) % RH; $U = \sqrt{0.1 \times P_{85} \times R} \le 100 \text{ V};$ 1000 h	± (2 % R + 0.1 Ω)
4.23	-	Climatic sequence:	-	
4.23.2	2 (Bb)	dry heat	125 °C; 16 h	
4.23.3	30 (Db)	damp heat, cyclic	55 °C; 24 h; ≥ 90 % RH; 1 cycle	
4.23.4	1 (Ab)	cold	-55 °C; 2 h	± (2 % R + 0.1 Ω)
4.23.5	13 (M)	low air pressure	8.5 kPa; 2 h; (25 ± 10) °C	,
4.23.6	30 (Db)	damp heat, cyclic	55 °C; 24 h; ≥ 90 % RH; 5 cycles	
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R} \le U_{\text{max.}}; 1 \text{ min}$	
-	1 (Aa)	Cold	-55 °C; 2 h	\pm (0.5 % R + 0.05 Ω)



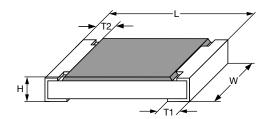
EN 60115-1 CLAUSE	IEC 60068-2 ⁽¹⁾ TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (△R)
			Stability for product types:	STABILITY CLASS 2 OR BETTER
			RCA-HP e3	1 Ω to 1 M Ω
4.19	14 (Na)	Rapid change of temperature	30 min at -55 °C and 30 min at 125 °C; 1000 cycles	\pm (1 % R + 0.05 Ω) no visible damage
4.13	-	Short time overload	U = 2.5 x $\sqrt{P_{70} \times R} \le 2 \times U_{\text{max.}}$; whichever is the less severe; 5 s	± (2 % R + 0.05 Ω)
4.27	-	Single pulse high voltage overload	Severity no. 4: $U = 10 \text{ x } \sqrt{P_{70} \text{ x } R}$ or $U = 2 \text{ x } U_{\text{max.}}$; whichever is the less severe; 10 pulses 10 µs/700 µs	\pm (1 % R + 0.05 Ω) no visible damage
4.39	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R} \text{ or } $ $U = 2 \times U_{\text{max.}};$ whichever is the less severe; $0.1 \text{ s on; } 2.5 \text{ s off;}$ 1000 cycles	\pm (1 % R + 0.05 Ω) no visible damage
4.38	-	Electrostatic discharge (human body model)	IEC 61340-3-1 ⁽¹⁾ ; 3 pos. + 3 neg. discharges; ESD voltage acc. to the size	± (1 % <i>R</i> + 0.05 Ω)
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude ≤ 1.5 mm or ≤ 200 m/s²; 7.5 h	\pm (0.5 % R + 0.05 Ω) no visible damage
4.17	58 (Td)	Solderability	Solder bath method; Sn60Pb40 non-activated flux; (235 ± 5) °C; (2 ± 0.2) s Solder bath method; Sn96.5Ag3Cu0.5 non-activated flux; (245 ± 5) °C; (3 ± 0.3) s	Good tinning (≥ 95 % covered) no visible damage
4.18	58 (Td)	Resistance to soldering heat	Solder bath method (260 ± 5) °C; (10 ± 1) s	± (0.5 % R + 0.05 Ω)
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; +50 °C; method 2	No visible damage
4.32	21 (Uu ₃)	Shear (adhesion)	RCA0402-HP: 9 N RCA0603-HP to RCA2512-HP: 17.7 N	No visible damage
4.33	21 (Uu ₁)	Substrate bending	Depth 2 mm; 3 times	\pm (0.25 % R + 0.05 Ω) no visible damage, no open circuit in bent positio
4.7	-	Voltage proof	$U = 1.4 \times U_{ins}$; 60 s	No flashover or breakdown
4.35	-	Flammability, needle flame test	IEC 60695-11-5 ⁽¹⁾ ; 10 s	No burning after 30 s

Note

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents

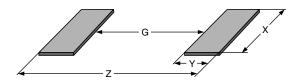


DIMENSIONS



DIMENSIONS AND MASS									
TYPE / SIZE	L (mm)	W (mm)	H (mm)	T1 (mm)	T2 (mm)	MASS (mg)			
RCA0402-HP e3	1.0 ± 0.05	0.5 ± 0.05	0.3 ± 0.10	0.25 ± 0.10	0.2 ± 0.10	0.65			
RCA0603-HP e3	1.6 ± 0.10	0.85 ± 0.10	0.45 ± 0.10	0.3 ± 0.20	0.3 ± 0.20	2			
RCA0805-HP e3	2.0 ± 0.15	1.25 ± 0.15	0.5 ± 0.10	0.4 ± 0.20	0.35 ± 0.20	5.5			
RCA1206-HP e3	3.1 ± 0.20	1.6 ± 0.15	0.5 ± 0.15	0.5 ± 0.20	0.45 ± 0.20	10			
RCA1210-HP e3	3.2 ± 0.20	2.5 ± 0.20	0.6 ± 0.10	0.45 ± 0.20	0.4 ± 0.20	18			
RCA1218-HP e3	3.1 ± 0.20	4.6 ± 0.20	0.6 ± 0.10	0.45 ± 0.20	0.4 ± 0.20	31			
RCA2010-HP e3	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.10	0.6 ± 0.20	0.6 ± 0.20	25.5			
RCA2512-HP e3	6.3 ± 0.20	3.15 ± 0.15	0.6 ± 0.10	0.6 ± 0.20	0.6 ± 0.20	42			

SOLDER PAD DIMENSIONS



RECOMMENDED SOLDER PAD DIMENSIONS									
TYPE / SIZE		WAVE SO	LDERING		REFLOW SOLDERING				
	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)	
RCA0402-HP e3	-	-	-	-	0.45	0.6	0.6	1.65	
RCA0603-HP e3	0.65	1.10	1.25	2.85	0.75	0.75	1.00	2.25	
RCA0805-HP e3	0.90	1.30	1.60	3.50	1.00	0.95	1.45	2.90	
RCA1206-HP e3	1.40	1.40	1.95	4.20	1.50	1.05	1.8	3.60	
RCA1210-HP e3	1.80	1.45	2.95	4.70	1.70	1.10	2.80	3.90	
RCA1218-HP e3	1.60	1.50	5.10	4.60	1.70	1.10	4.90	3.90	
RCA2010-HP e3	3.60	1.65	2.85	6.90	3.70	1.20	2.70	6.10	
RCA2512-HP e3	4.90	1.60	3.50	8.10	5.00	1.25	3.35	7.50	

Notes

[•] The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g in standards IEC 61188-5-x (1) or in publication IPC-7351.

Still, the given solder pad dimensions will be found adequate for most general applications

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents



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CR-05FL7--150R CR-05FL7--698K CR-12JP4--680R CRCW04021K20FKEE CRCW04028R20JNEE CRCW06032K10FKEC

CRCW06036K80FKEE M55342K03B499DRS6 M55342K06B6E19RWL M55342K09B5D62RS6 M55342M06B26E7RS3 742C083750JTR

MCR01MRTF1001 MCR01MZPF1202 MCR01MZPF1601 MCR01MZPF1800 MCR01MZPF6201 MCR01MZPF9102 MCR01MZPJ121

MCR01MZPJ125 MCR01MZPJ751 MCR03EZHJ103 MCR03EZPFX2004 MCR03EZPJ270 MCR03EZPJ821 MCR10EZPF1102

MCR10EZPF2700 MCR18EZPJ330 RC1005F1152CS RC1005F1372CS RC1005F2052CS RC1005F471CS RC1005F4751CS

RC1005F5621CS RC1005F6041CS RC1005J121CS RC1005J122CS RC1005J180CS RC1005J181CS RC1005J202CS RC1005J391CS

RC1005J512CS RC1005J683CS RC1005J823CS RC1608F333CS RC1608F5110CS RC1608J121CS RC2012F2493CS RC2012F2740CS

RC2012J105CS